

SPECIFICATION AND PERFORMANCE

Series 115T-series2	File	115T-series2-spec_1	Date	2021/04/01
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of below table

P/N	Descriptions
115T-AAA1	SIM Card Socket, Bar Push w/switch, w/o post, 1u", Reel, 6 Pin
115T-BAA1	SIM Card Socket, Bar Push w/switch, w/o post, 1u", Reel, 8 Pin
115T-AAB1	SIM Card Socket, Bar Push w/switch, 1u", Reel, 6 Pin
115T-BAB1	SIM Card Socket, Bar Push w/switch, 1u", Reel, 8 Pin
115-00004	SIM Card Tray for 115T Series, Nylon Black

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIAL AND FINISH			
HOUSING	LCP, UL94V-0, Black		
CONTACT	Phosphor Bronze, selective 1u" min. Gold Plating on contact area, 50u" min. Tin plating on solder tails, under plating 50u" min. Nickel plating		
HOOK	Stainless Steel		
SPRING	Stainless Steel		
KNOB	LCP, UL94V-0, Yellow		
LINK	Stainless Steel		
RIVET	Brass, Nickel plating		
TRAY of SIM card	Insulator: Thermoplastic, UL94V-0, Black		
(P/N:115-00004)	Shield: Copper alloy, Gold plating over Nickel		
Rating	Current Rating: 1A max Voltage Rating: 50VAC max.		

	FLEATDLAN		
		Storage Temperature Range: -40°C to +85°C	
R	ating	Operating Temperature Range: -40°C to +85°C	

ELECTRICAL			
Item	Requirement	Test Condition	
Contact Resistance	$50m\Omega$ (Initial) ΔR = 40 mΩ Max.	Mate connectors with dry circuit (20 mV, 100mA Max.) EIA-364-23	
Insulation Resistance	1000MΩ MIN. (Initial)	After 500 VDC for 1 minute, measure the	

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	500MΩ MIN. (Final)	insulation resistance between the adjacent contacts of mated and unmated connector assemblies. EIA-364-21
Dielectric Withstanding Voltage	No shorting, breakdown, flashover or other damage.	Apply 500 VAC for one minute at sea level on unmated connectors, less than 0.5 mA leakage current. EIA-364-20

MECHANICAL			
Item	Requirement	Test Condition	
Durability	No evidence of damage The electrical performances should meet the spec. specified	Mating/ un-mating: 5000 cycles Cycle Rate: 400 to 600 cycles per hour. EIA-364-09	
Contact Normal Force	0.5N Min. per pin	0.10mm gap to housing surface test speed: 25±3mm/minute	

ENVIRONMENTAL		
Item	Requirement	Test Condition
Humidity	No evidence of damage	Ambient Temp.: 40 ±2 °C
	The electrical	Relative humidity: 90 to 95%RH
	performances should	Duration time: 96 hours
	meet the spec. specified	EIA-364-31
Salt Spray	No mechanical damage;	Temperature: 35±2°C
	No harmful corrosion	NaCI: 5%
	occurs on contact.	Duration: 48H
		EIA-364-26
Low Temperature	No evidence of damage	Chamber Temperature: -40±3°C
Resistance	The electrical	Duration: 96 hours
	performances should	Dummy card engaged during test
	meet the spec. specified	EIA-364, TP-59
Temperature Life	No evidence of damage	Chamber Temperature: 85±3°C
	The electrical	Duration: 96 hours
	performances should	Dummy card engaged during test
	meet the spec. specified	EIA-364,TP-17
Vibration	No electrical discontinuity	Frequency Range: 10-55-10
	greater than 100n sec.	Total Amplitude: 1.52 mm pp or 98.1m/s
	shall occur.	Duration: 2 hrs tree axes (6 hrs in total)
		EIA-364,TP-28
Shock	No electrical discontinuity	Accelerated Velocity: 50 G (490 s/m) Waveform:
	greater than 100n sec.	Semi Sine Duration: 11 m sec.
	shall occur.	No of Shocks: 3/dir., 3 axis, (18 in total),
		EIA-364, TP-27

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SOLDER ABILITY		
Item	Requirement	Test Condition
Solderability	Wet Solder Coverage: 90% Min.	Solder Temperature: 245±3°C Immersion Duration: 3±0.5 sec. Solder: Sn-3Ag-0.5Cu Flux: RMA 25%
Solder Heat Resistance	No evidence of deformation or fusion of housing and no physical damage.	Test connector on PC Board. Pre-heat: 150 to 180°C for 90 sec. Solder Heat 230°C for 30 sec. Peak Temp.: 255°C±5°C, 10 sec.
260 MAX 250 230 MIN 200 180 100 100 0	Pre-Heating 90±30sec	Heat 30±10sec